

This Page Is Inserted by IFW Operations  
and is not a part of the Official Record

## **BEST AVAILABLE IMAGES**

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

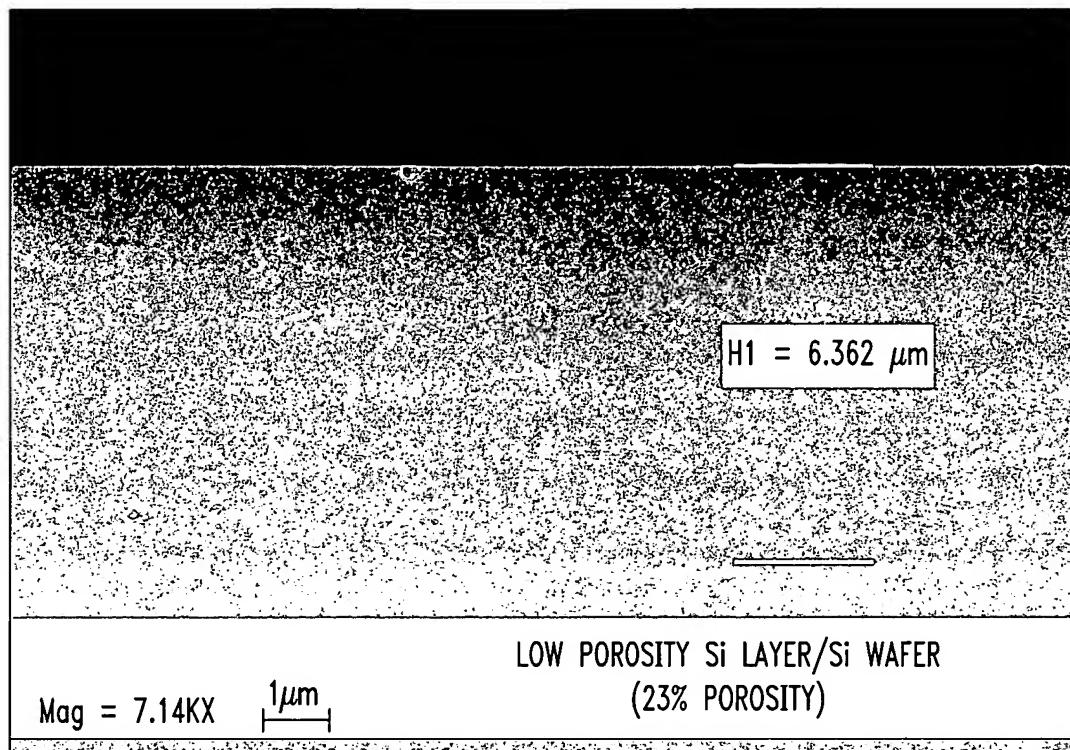
- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

**IMAGES ARE BEST AVAILABLE COPY.**

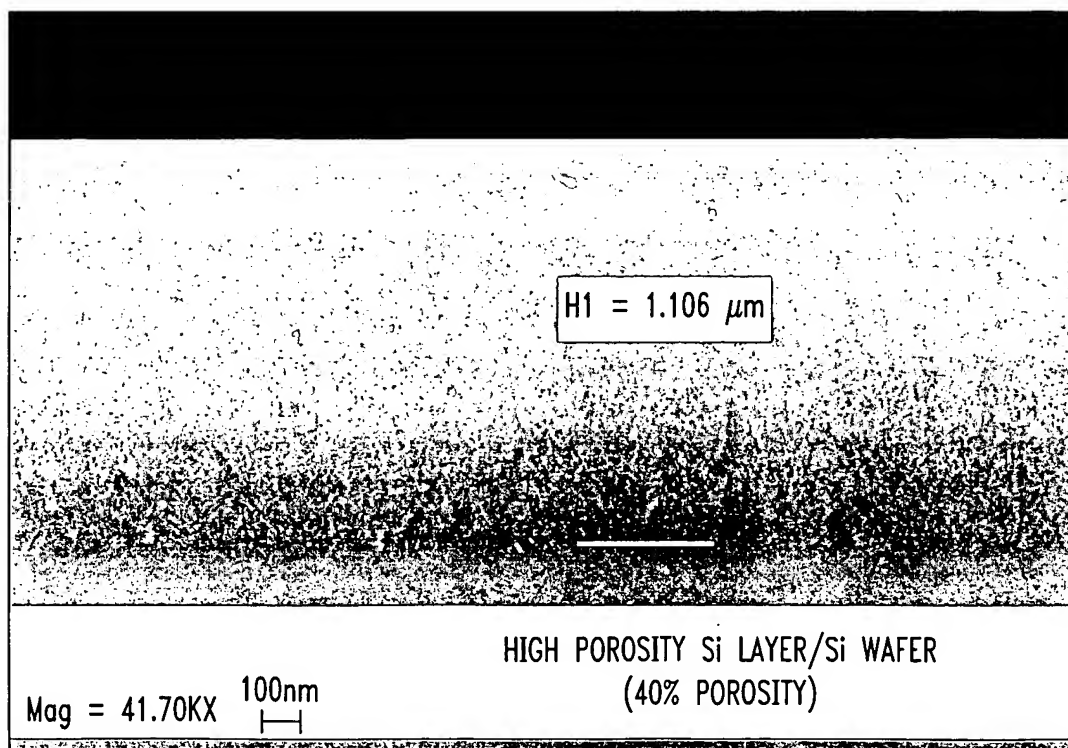
**As rescanning documents *will not* correct images,  
please do not report the images to the  
Image Problem Mailbox.**



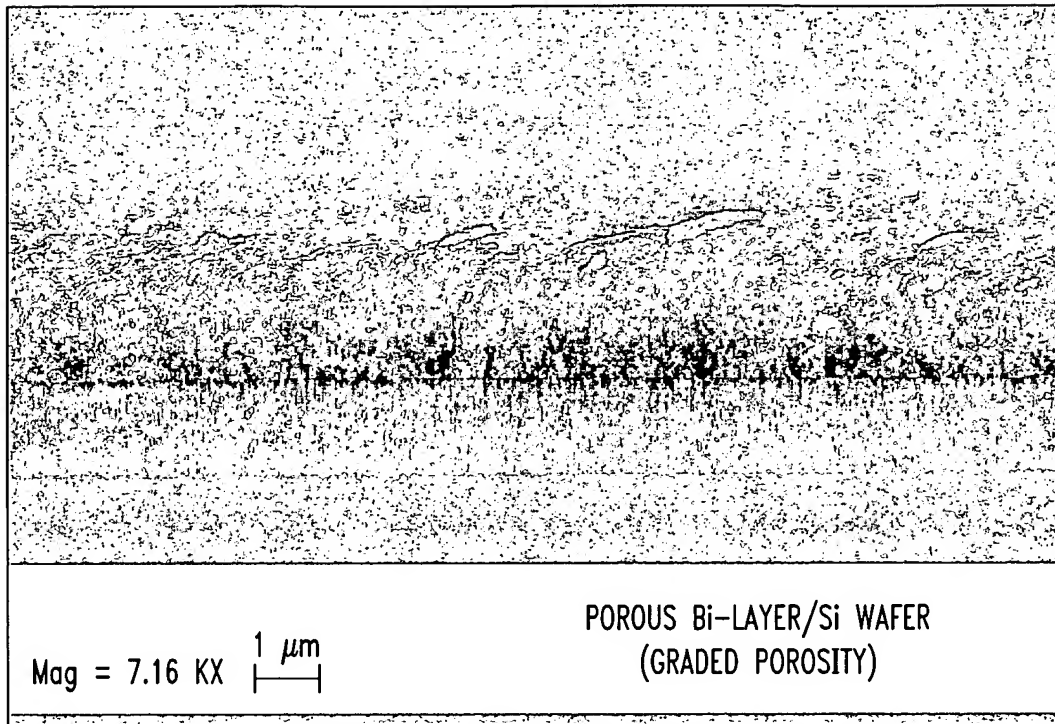
*FIG. 1a*



*FIG. 1b*

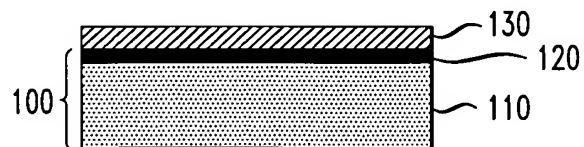


*FIG. 1c*



*FIG. 2*

SUBSTRATE BASED ON USE OF THE POROUS-Si LAYER AND  
SUBSEQUENT REGROWTH OF epi-Si LAYER TO CREATE SOI WAFERS



*FIG. 3*

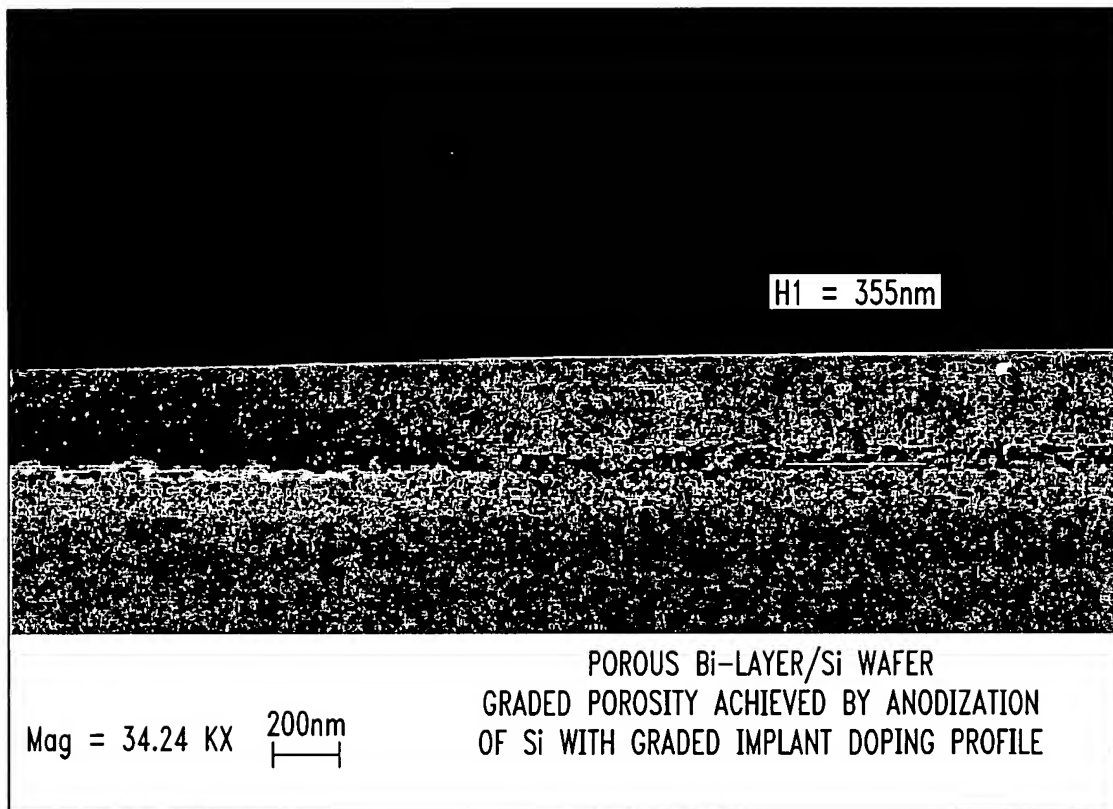
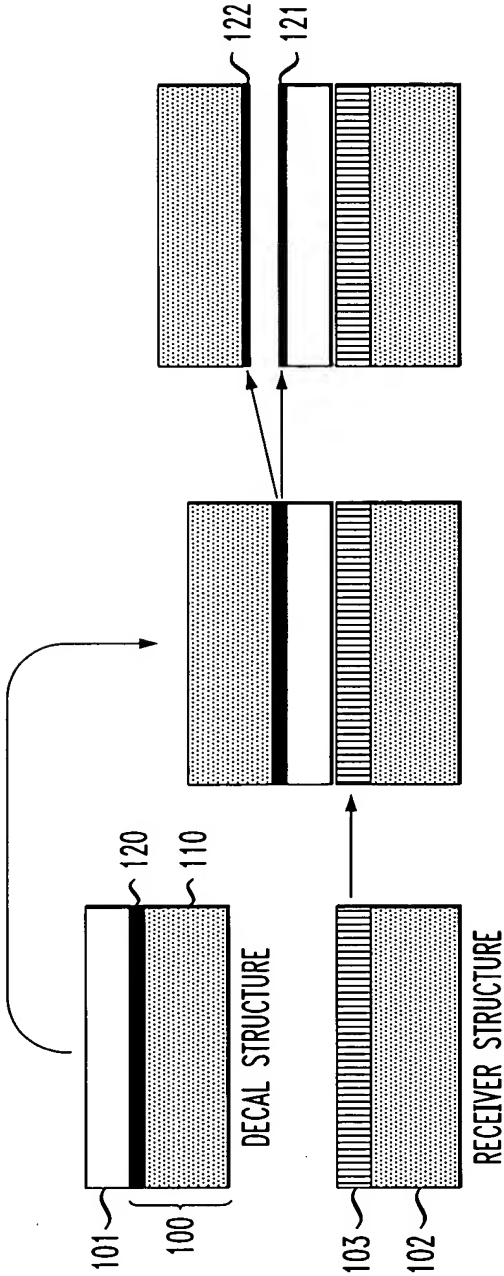


FIG. 4

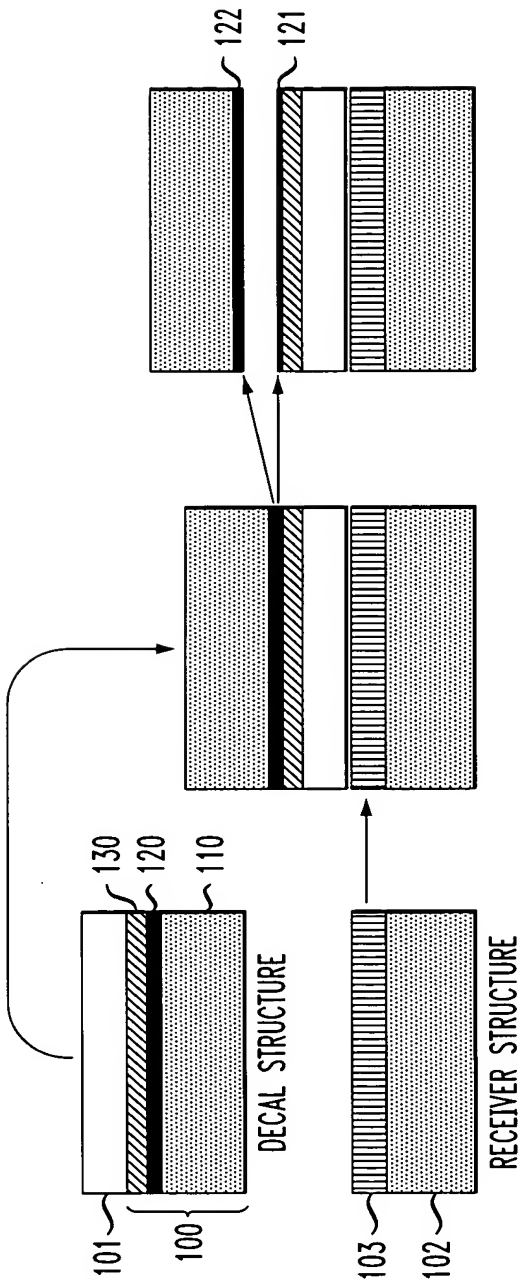


#1 STEP: BUILD OF DECAL  
AND RECEIVER STRUCTURES

#2 STEP: MATING OF DECAL  
AND RECEIVER STRUCTURES

#3 STEP: RELEASE OF CARRIER  
SUBSTRATE VIA PEELING

FIG. 5



#1 STEP: BUILD OF DECAL  
AND RECEIVER STRUCTURES

#2 STEP: MATING OF DECAL  
AND RECEIVER STRUCTURES

#3 STEP: RELEASE OF CARRIER  
SUBSTRATE VIA PEELING